



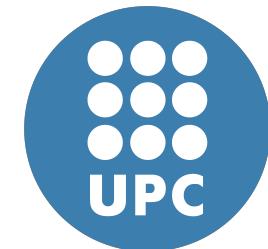
STT-MRAM Cell Reliability Evaluation under Process, Voltage and Temperature (PVT) Variations

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Memories Today

	SRAM	DRAM	Flash
Cell Size	$120F^2$	$4-6F^2$	$4-5 F^2$
Read Access Time	<1ns	20ns	25,000ns
Write1 Access Time	<1n 0ns	0ns	200,000ns
Write0 Access Time	<1ns	20ns	200,000ns
Endurance	$>10^{12}$	10^{15}	10^4
Non-volatility	NO	NO	

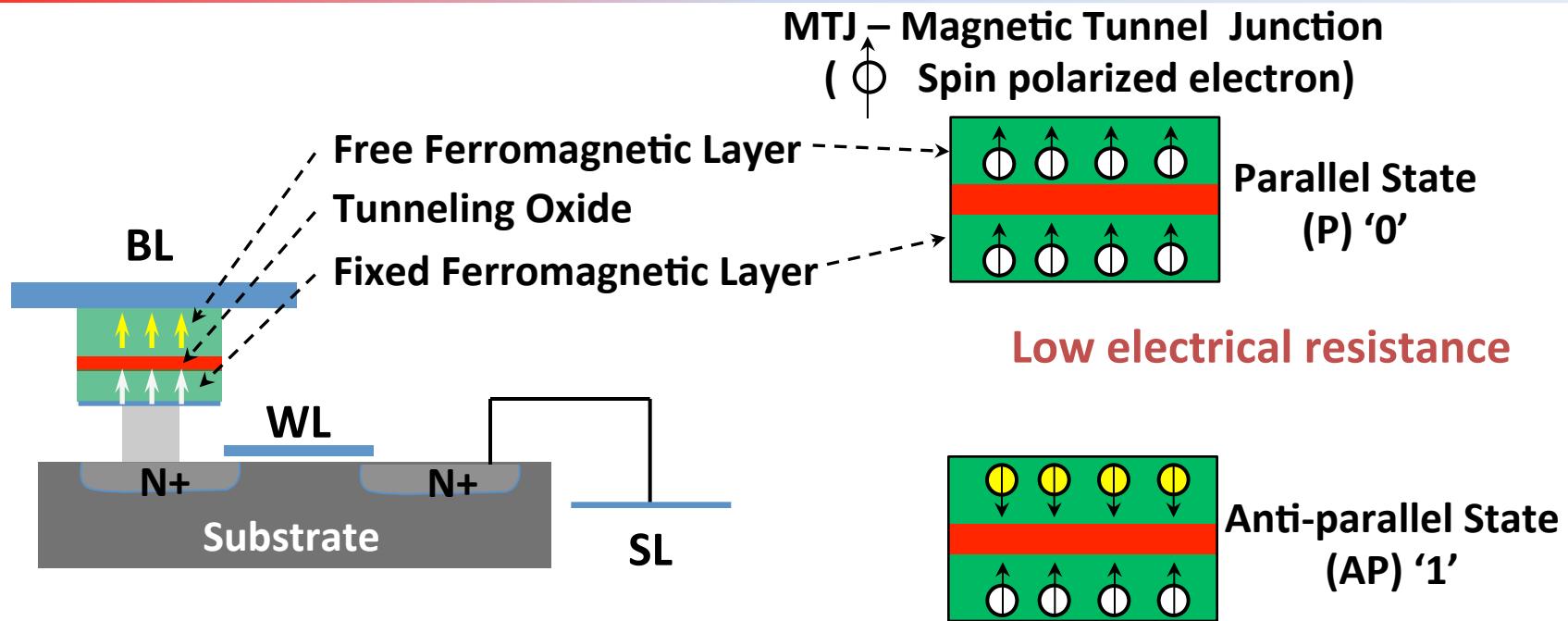
Outline

- **Introduction to STT-MRAM cell**
- **STT-MRAM cell operation principle**
- **Failure mechanisms of the STT-MRAM cell**
- **STT-MRAM cell reliability under PVT variations**
- **Conclusions**

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1T1MTJ STT-MRAM Cell

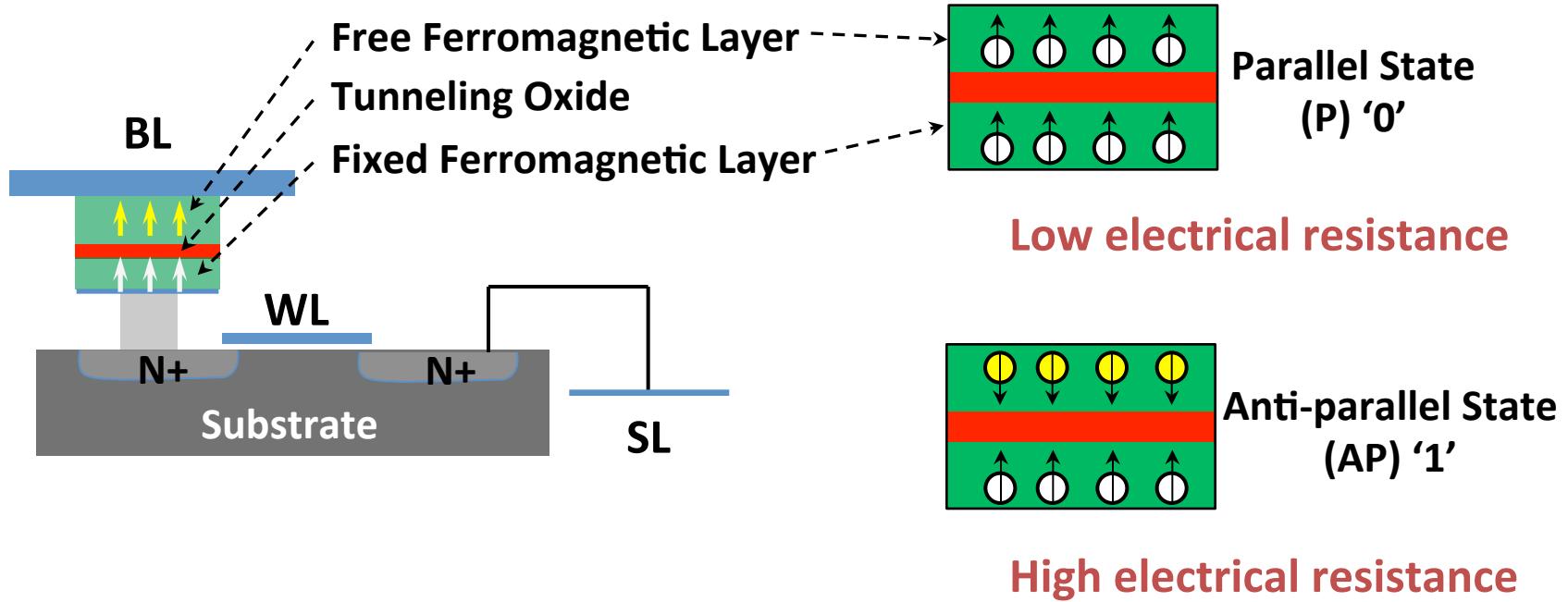


The orientation of the free layer:

- determines the **resistance** of the material
- can be changed by injecting **current**.

1T1MTJ STT-MRAM Cell

MTJ – Magnetic Tunnel Junction
(\rightarrow Spin polarized electron)



Main resiliency issues come from variations in:

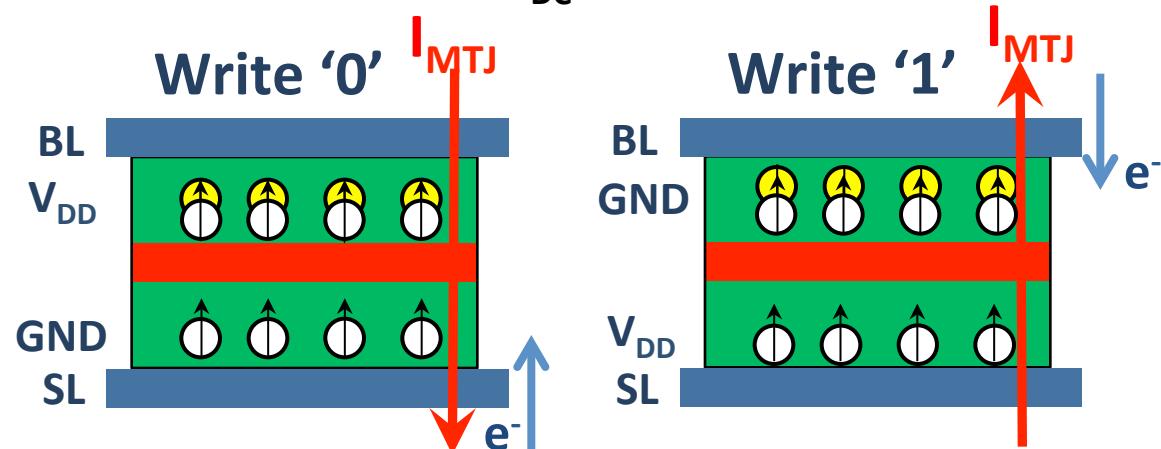
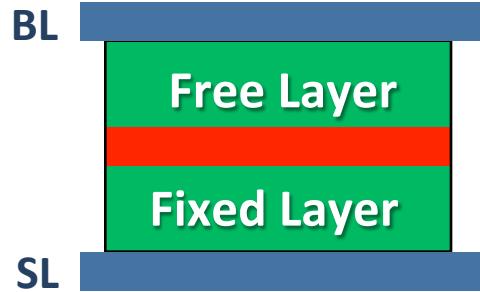
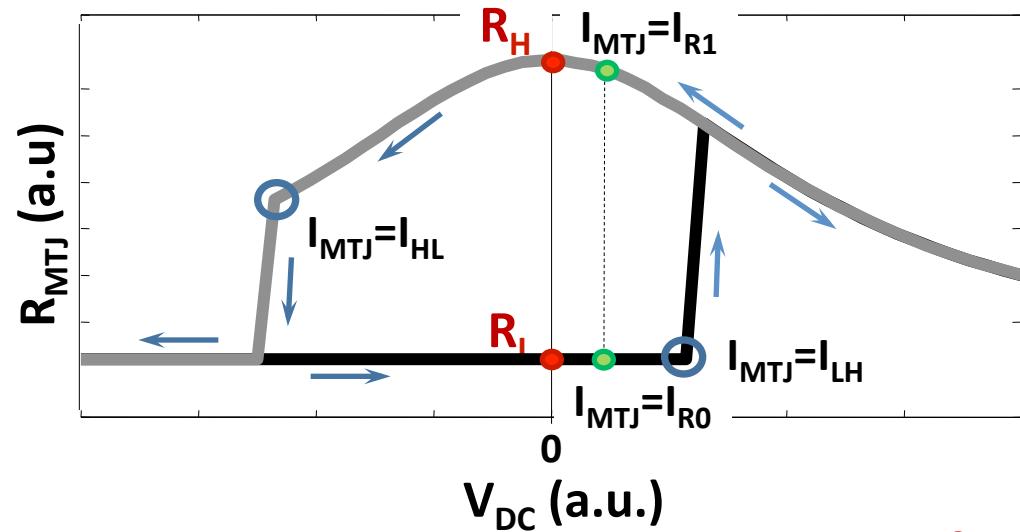
- Tunneling oxide thickness and cross-section area
- Free layer thickness

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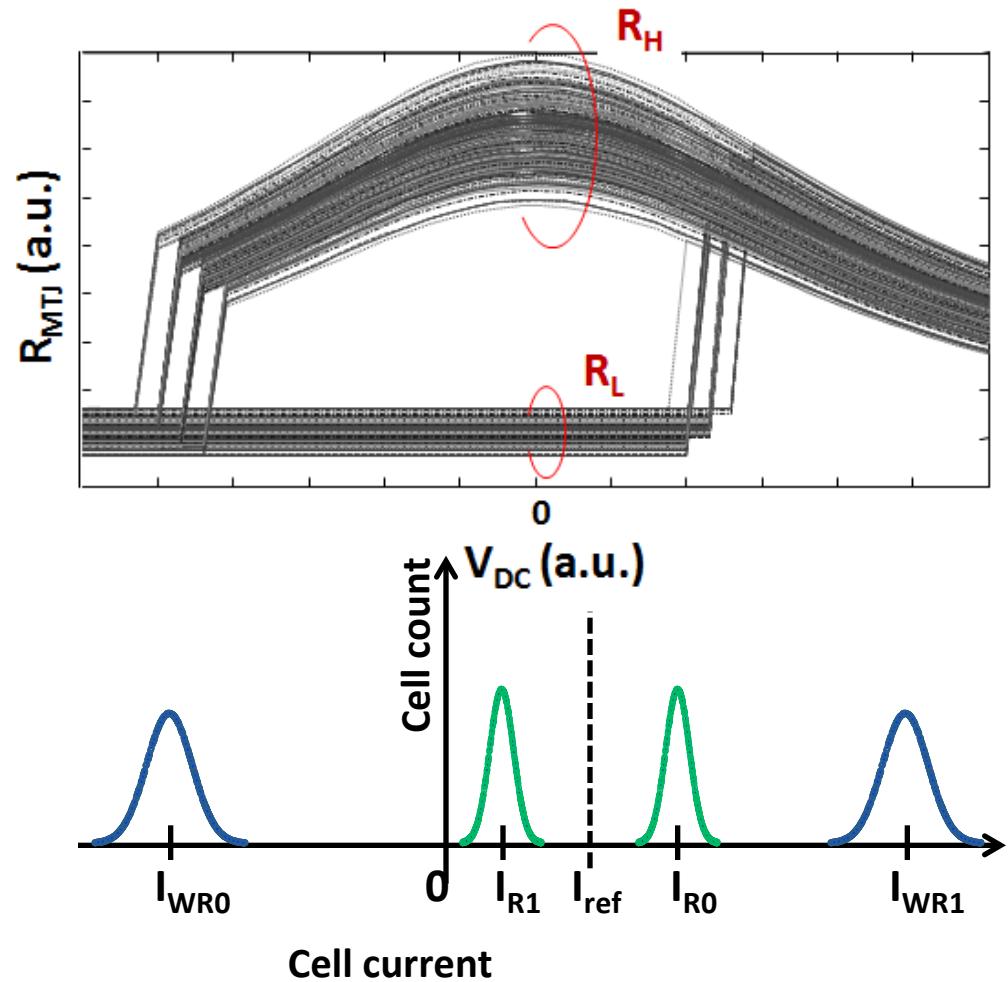
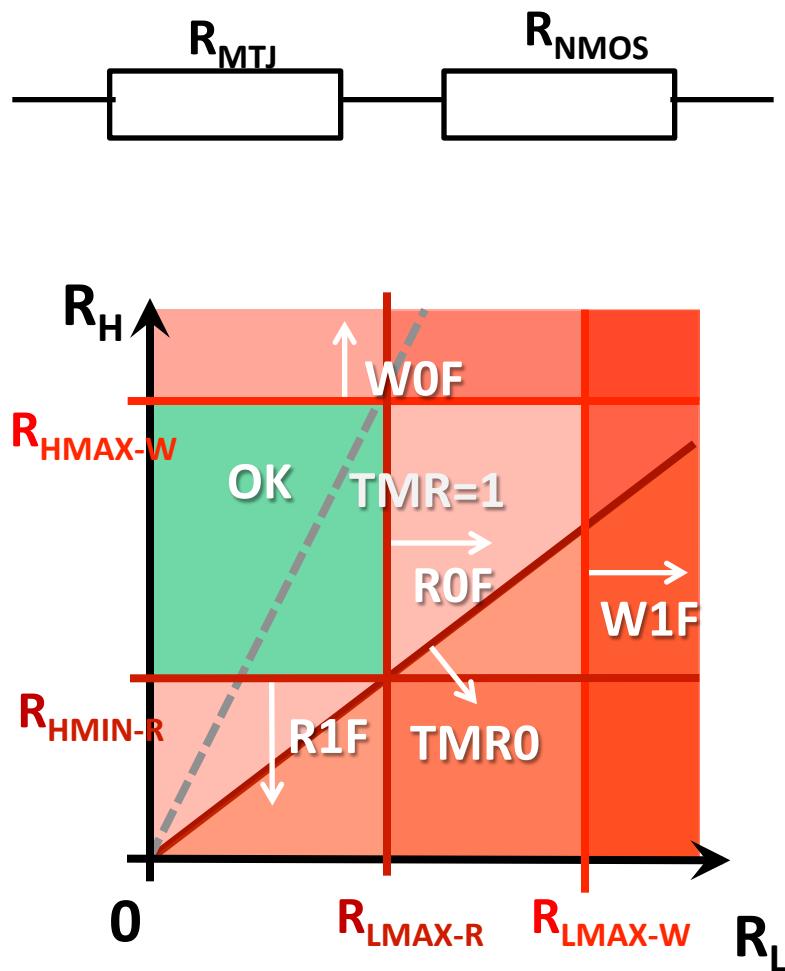
I_{HL} –high to low transition
 I_{LH} –low to high transition



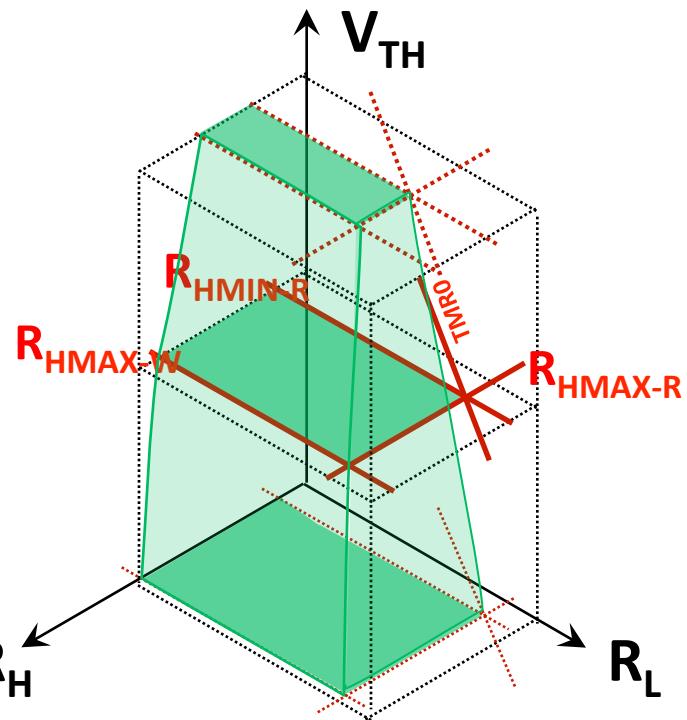
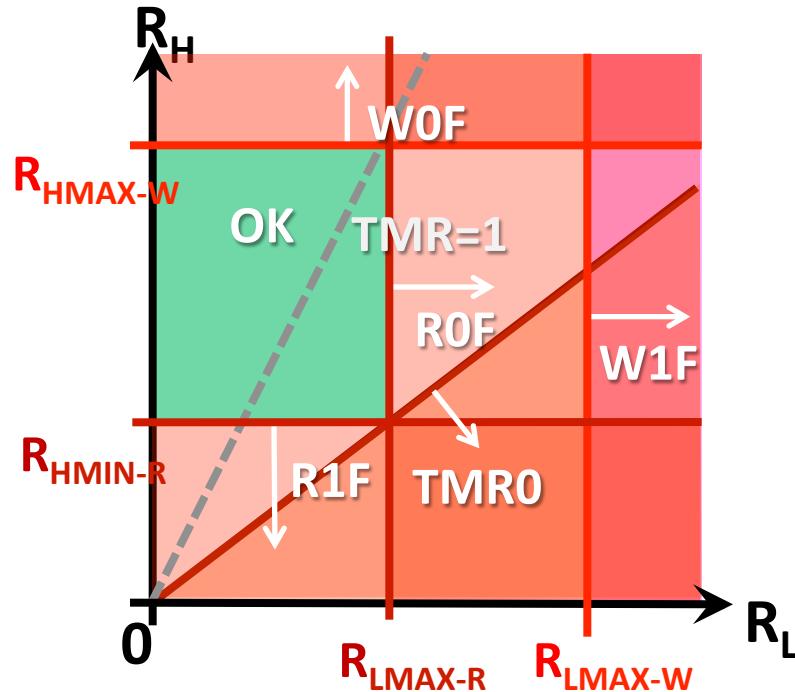
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STT MRAM Cell Failure Mechanisms

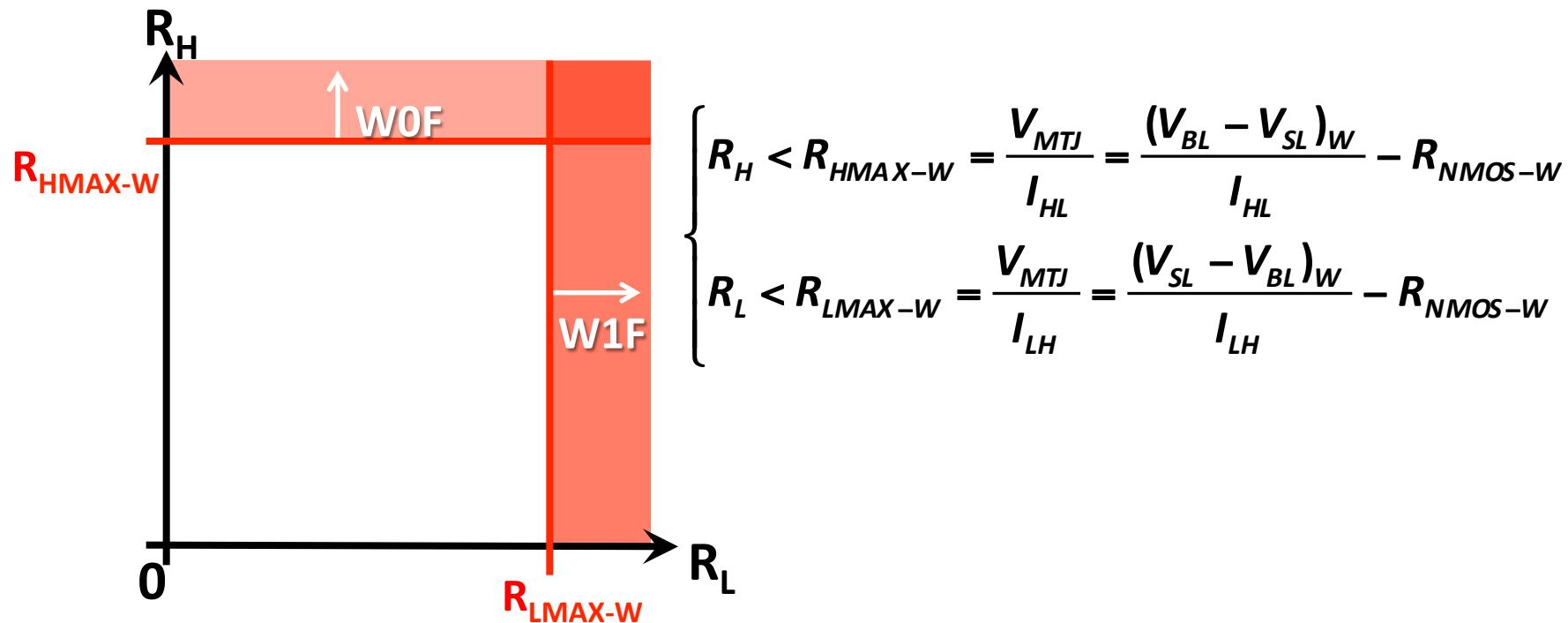


STT MRAM Cell Failure Mechanisms



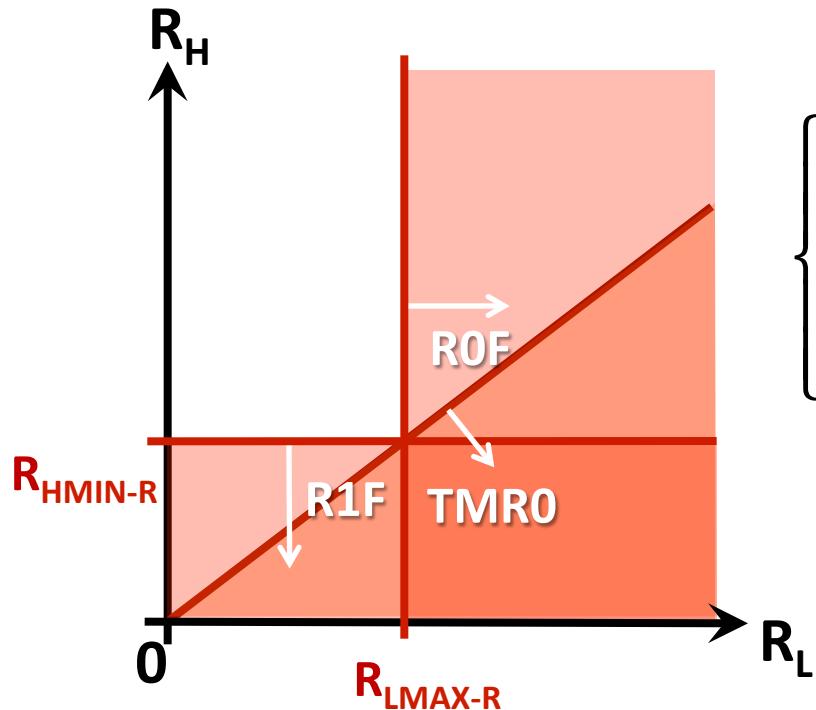
STT MRAM Cell Failure Mechanisms

- Failure during Write Operation (WF)



STT MRAM Cell Failure Mechanisms

- Failure during Read Operation



$$\begin{cases} R_H > R_{HMIN-R} = \frac{V_{MTJ}}{I_{REF}} = \frac{(V_{BL} - V_{SL})_R}{I_{REF}} - R_{NMOS-R} \\ R_L < R_{LMAX-R} = \frac{V_{MTJ}}{I_{REF}} = \frac{(V_{BL} - V_{BL})_R}{I_{REF}} - R_{NMOS-R} \end{cases}$$

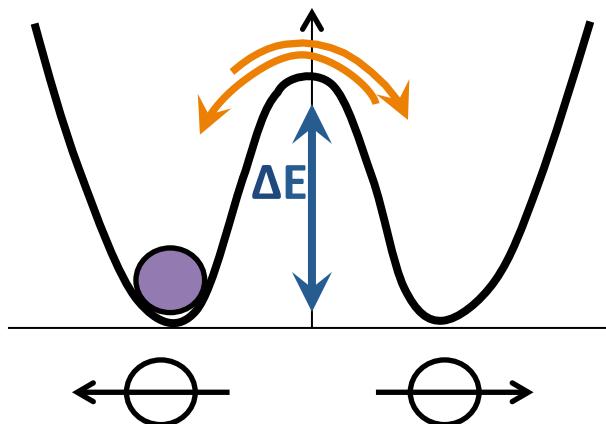
$$I_{REF} = \frac{I_{RH} + I_{RL}}{2}$$

$$R_L < R_{LMAX-R} = R_{HMIN-R} < R_H$$

STT MRAM Cell Failure Mechanisms

- STT-MRAM Cell Failure Probability in Data Retention

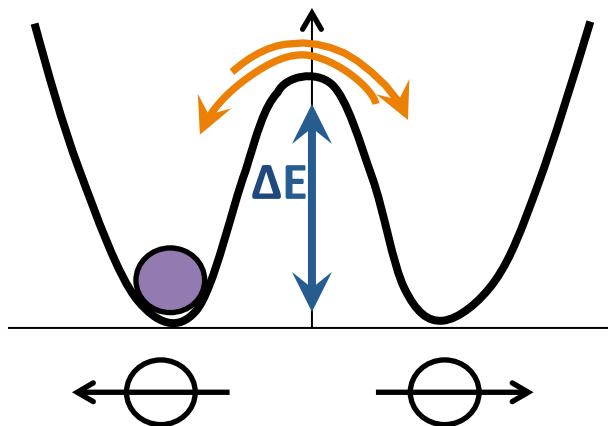
$$P(t) = 1 - \exp[(-Nt/\tau_0) \cdot \exp(-\Delta E/k_B T)]$$



STT MRAM Cell Failure Mechanisms

- STT-MRAM Cell Failure Probability in Read Operation

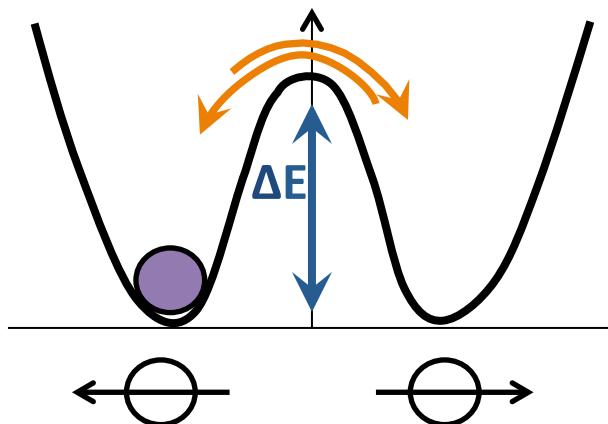
$$P(t) = 1 - \exp[(-Nt/\tau_0) \cdot \exp(-\Delta E(1 - (I_{read}/I_{oc})) / k_B T)]$$



STT MRAM Cell Failure Mechanisms

- STT-MRAM Cell Failure Probability in Write Operation

$$P(t) = \exp\left[(-Nt/\tau_0) \cdot \exp(-\Delta E(1 - (I_{\text{Write}}/I_{\text{OC}}))/k_B T)\right]$$

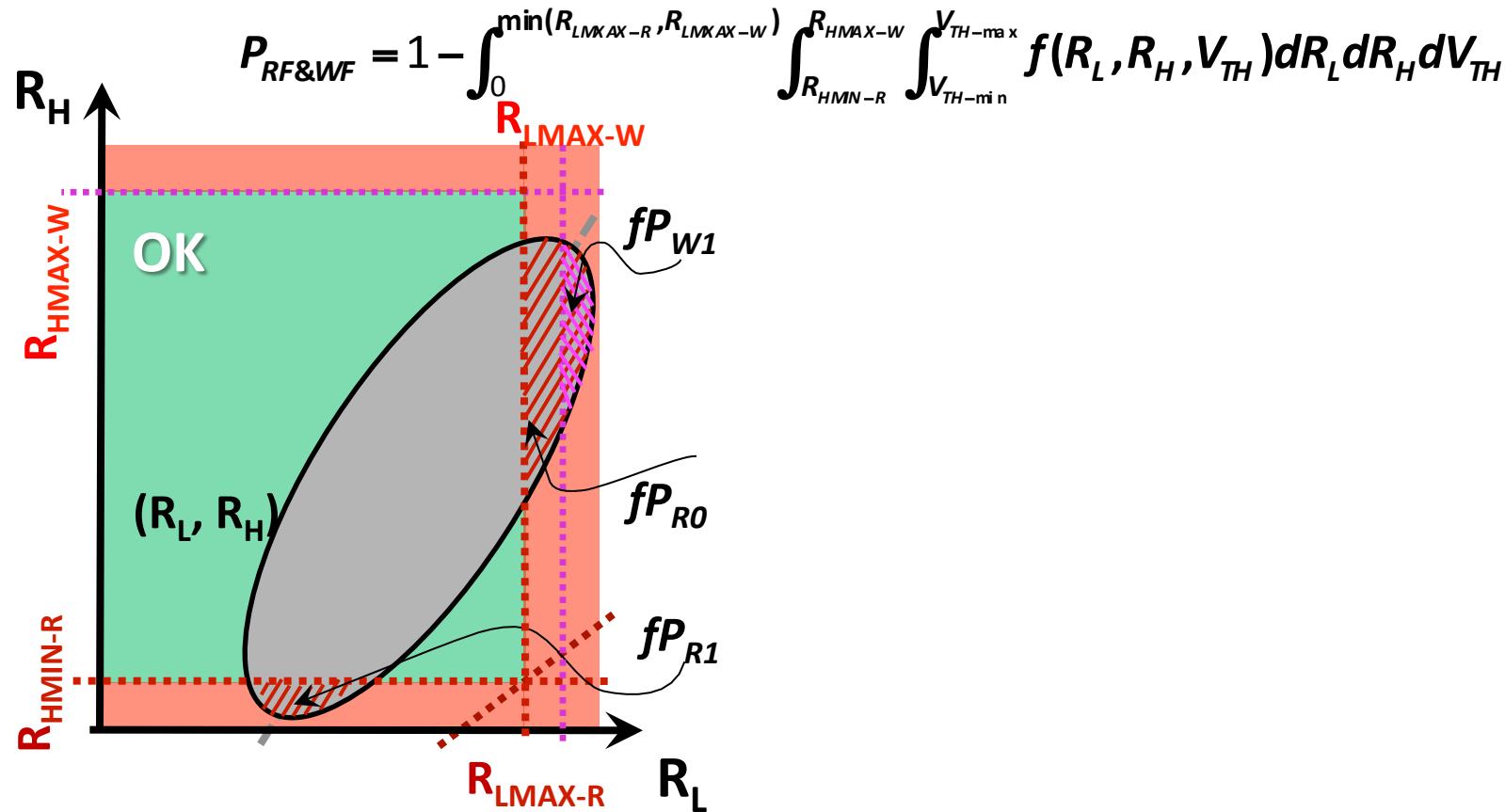


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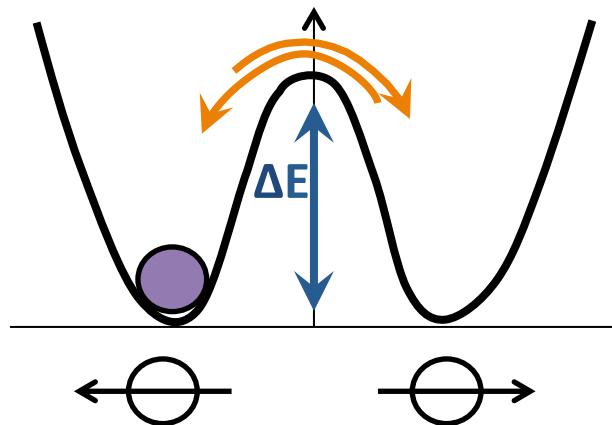
STT MRAM Cell Failure Probability

- STT-MRAM Cell Failure Probability



STT MRAM Cell Failure Probability

- STT-MRAM Cell Failure Probability in Data Retention

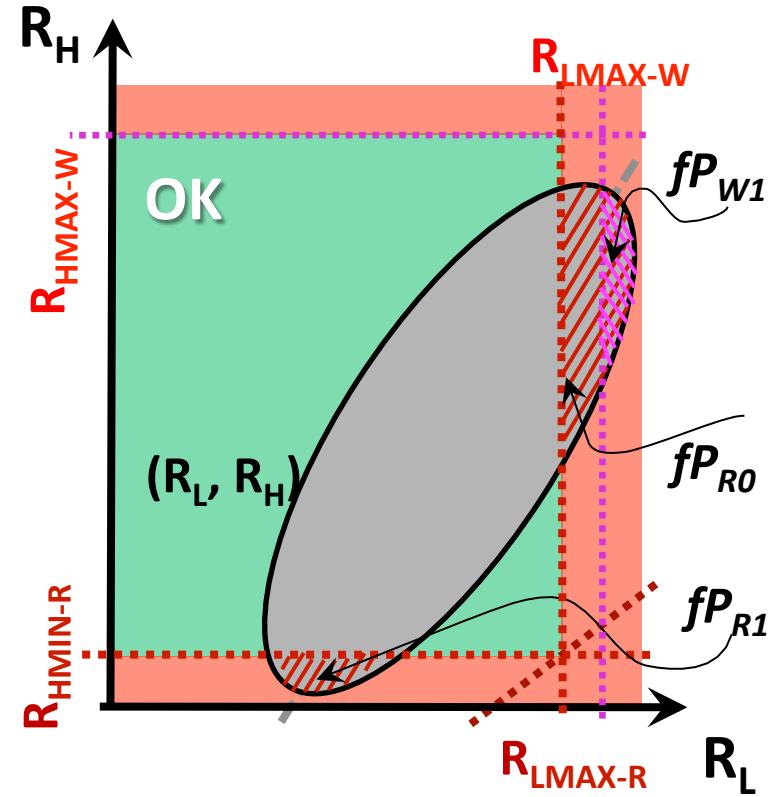
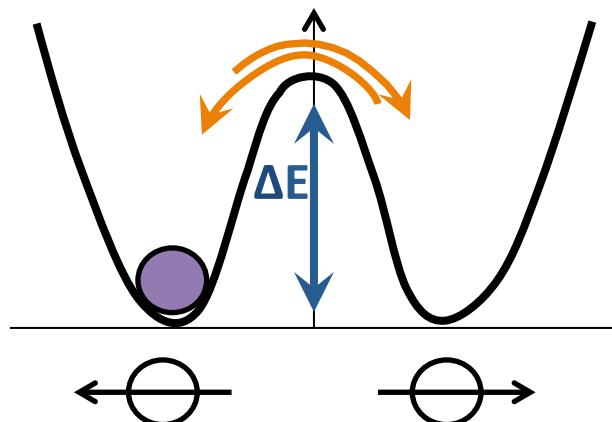


$$P(t) = 1 - \exp[(-Nt/\tau_0) \cdot \exp(-\Delta E/k_B T)]$$

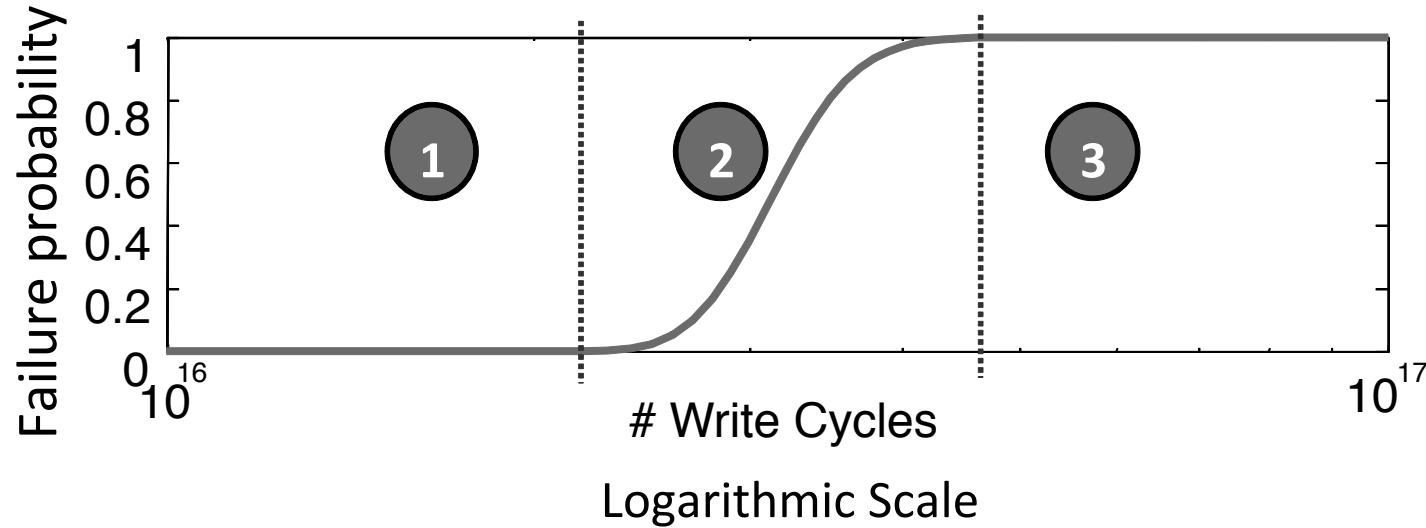
STT MRAM Robustness Probability

- STT-MRAM Cell Failure Probability

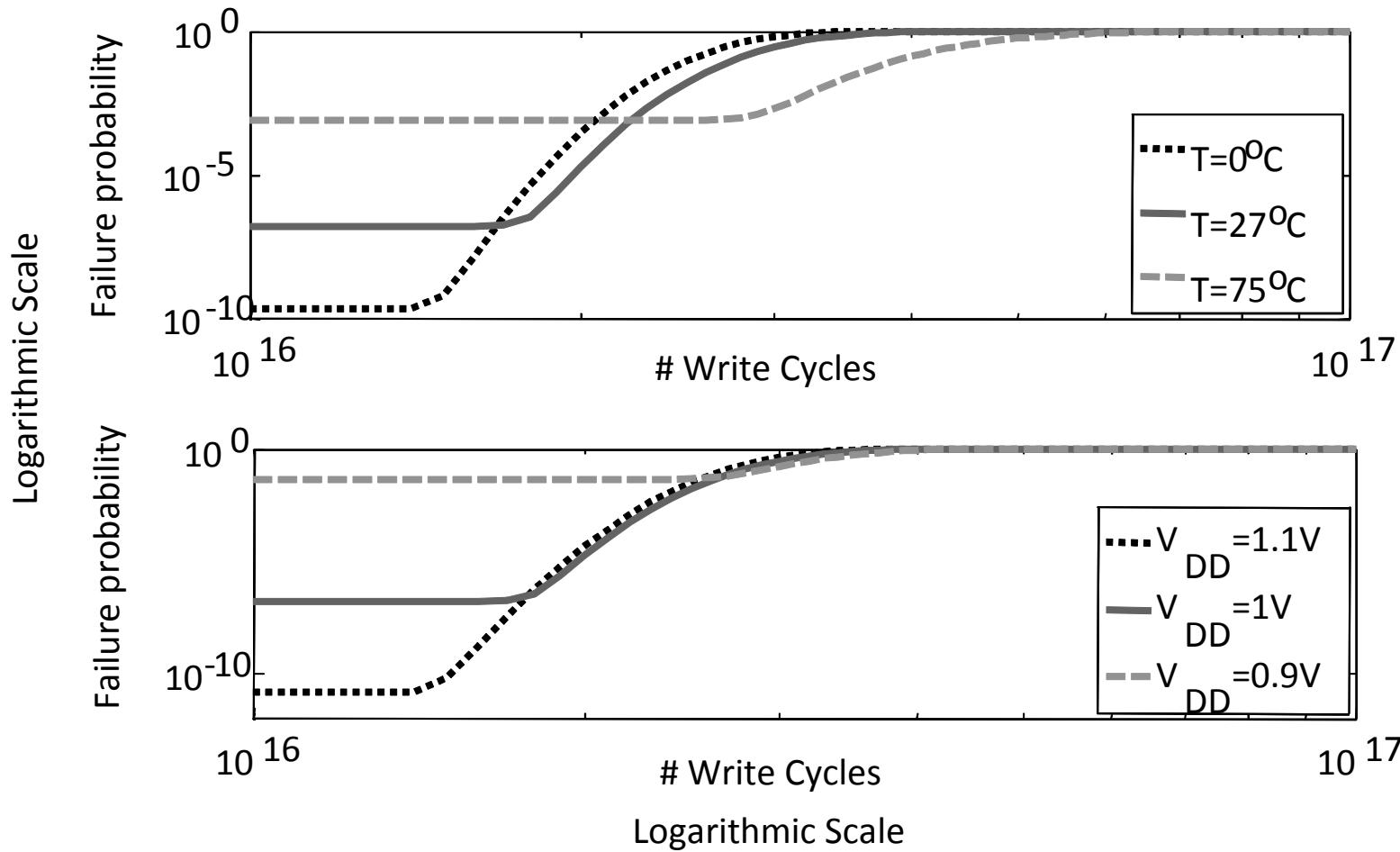
$$P_f = 1 - (1 - P_{RF\&WF}) \cdot (1 - P_{DRF})$$



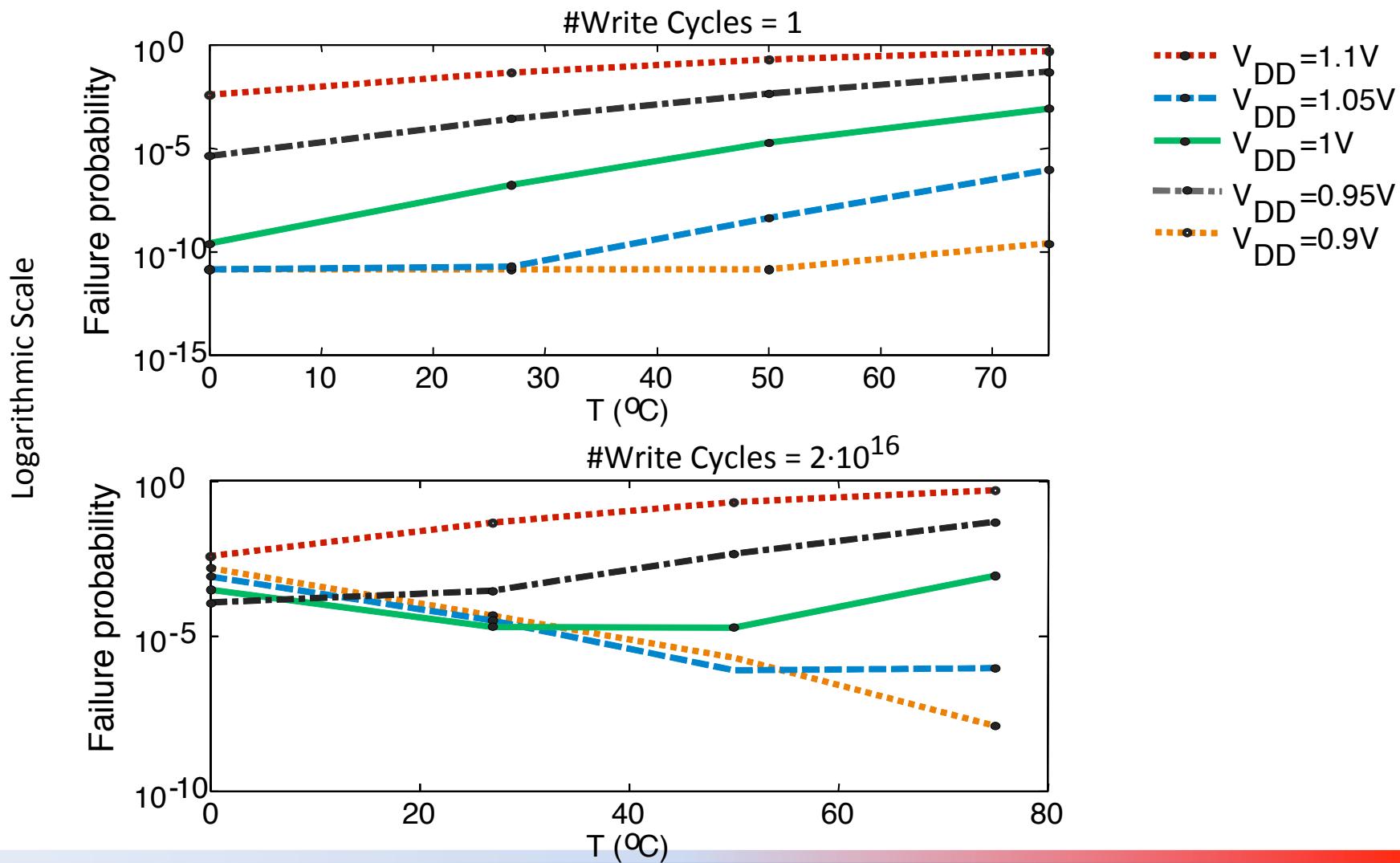
STT MRAM Cell Failure Probability



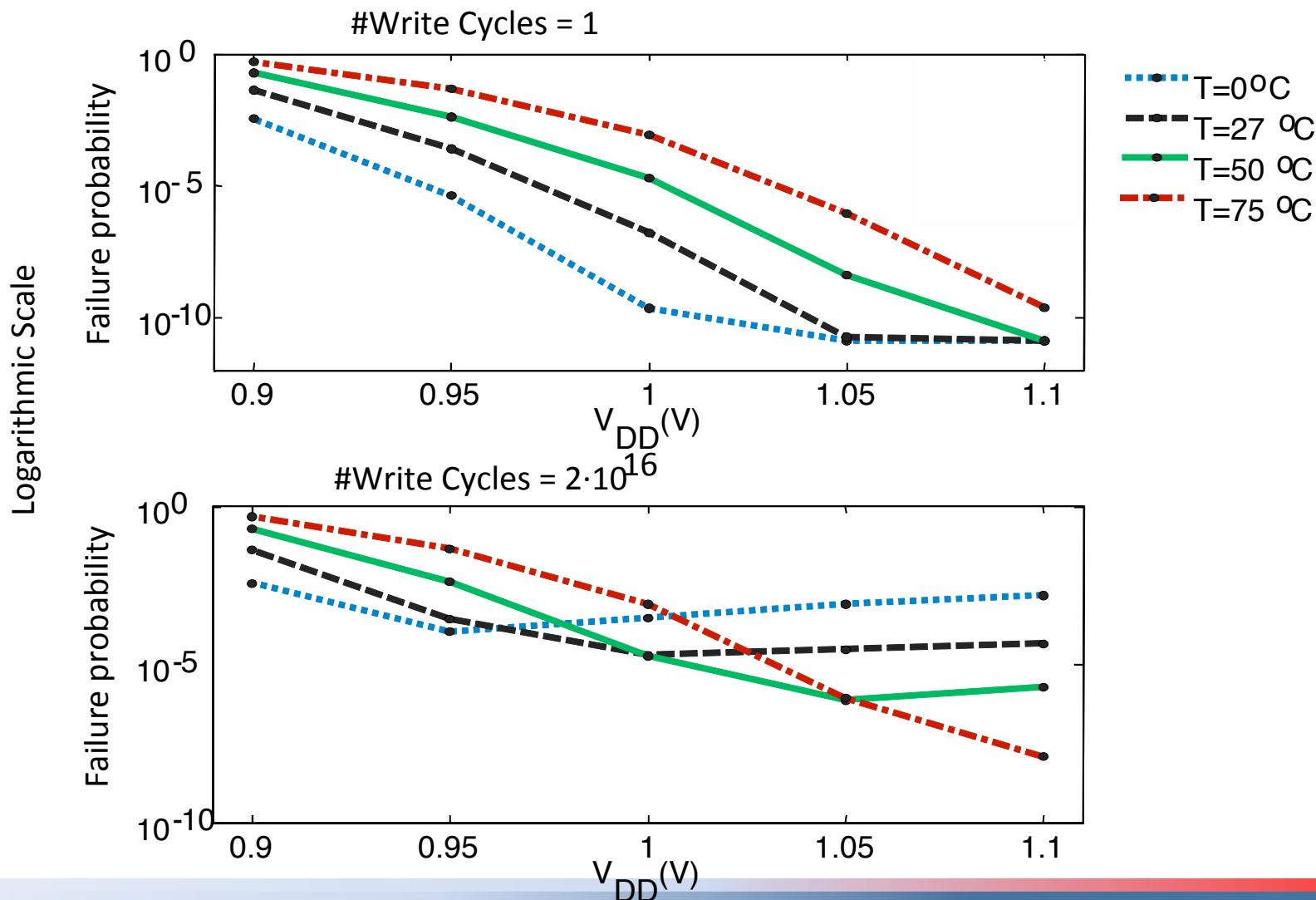
STT MRAM Cell Failure Probability



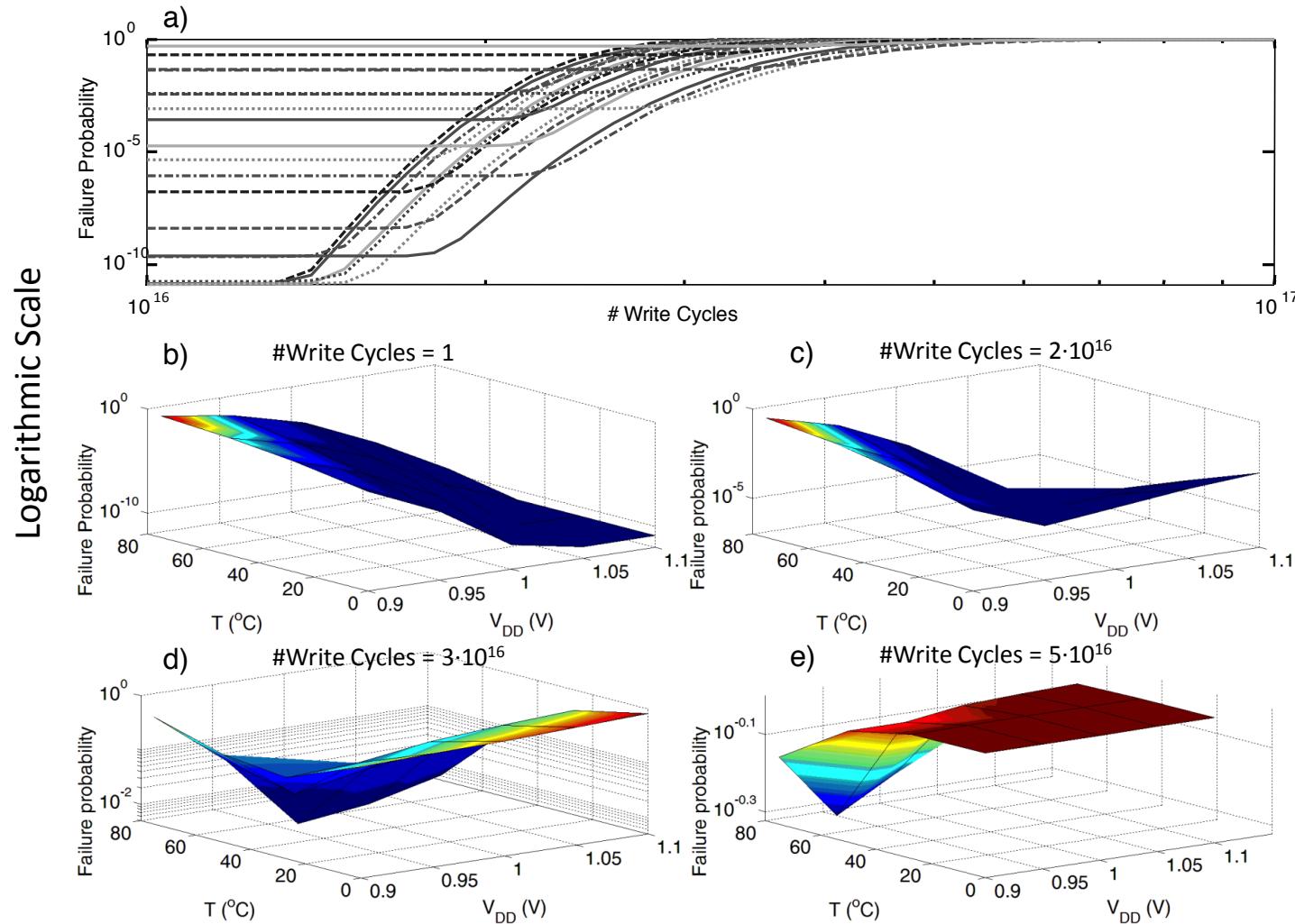
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STT MRAM Cell Failure Probability



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- methodology for STT-MRAM cell reliability prediction
- the joint effect of
 - fabrication- and aging-induced process variability
 - supply voltage variations
 - temperature variations